

LASER PROCESSING APPARATUS

ABSTRACT OF THE DISCLOSURE

A laser processing apparatus includes an unloading/loading mechanism for unloading a wafer from and loading a wafer into a cassette placed on a cassette placing stand, a chuck table for rotatably holding the wafer unloaded from the cassette by the unloading/loading mechanism, an image capturing unit for capturing an image of a wafer, and a control unit. The control unit controls the unloading/loading mechanism to orient a mark indicating the crystal orientation of a processed wafer in a predetermined direction different from a direction in which the mark of an unprocessed wafer in the cassette is oriented, when the unloading/loading mechanism houses the processed wafer into the cassette.

[Fig. 1]